5822134-4 ACTIVE

MICRO-EDGE

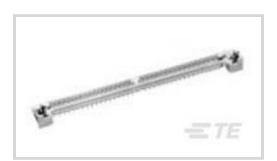
TE Internal #: 5822134-4

SIMM Sockets, 22° Module Orientation, 80 Position, Through Hole - Solder, 1.27mm [.05in] Centerline, 1 Row, Printed Circuit Board

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Connectors > Socket Connectors > Memory Sockets > SIMM Sockets



Module Orientation: 22°
Number of Positions: 80

PCB Mounting Style: Through Hole - Solder

Centerline (Pitch): 1.27 mm [.05 in]

Number of Rows: 1

Features

Product Type Features

Center Post	With
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket
Profile	Low

Configuration Features

Center Key	None
Number of Keys	1
Module Orientation	22°
Number of Positions	80
Number of Rows	1

Body Features

Ejector Location	None
Latch Material	Stainless Steel
Retention Post Location	Center
Latch Plating Material	Nickel

Contact Features

Socket Style	SIMM
Contact Underplating Material	Nickel



PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Current Rating (Max)	1 A
Contact Mating Area Plating Thickness	200 μin
Socket Type	Memory Card
Contact Mating Area Plating Material	Tin
Termination Features	
Insertion Style	Cam-In
Termination Post Length	2.92 mm, 3.56 mm[.115 in][.14 in]
Mechanical Attachment	
Polarization	Left
PCB Mounting Style	Through Hole - Solder
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP (Liquid Crystal Polymer)
Dimensions	
Center Retention Hole Diameter	1.63 mm[.064 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tube, Tube
Packaging Quantity	26
Product Compliance	

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant	
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EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought























Documents

Product Drawings

80 ME .050 L/P M/L PB-FREE

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5822134-4_B_c-5822134-4-b.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5822134-4_B_c-5822134-4-b.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5822134-4_B_c-5822134-4-b.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English

MICRO-EDGE SIMM (Single In-Line Memory Module) Connectors

English

Product Environmental Compliance

TE Material Declaration

English

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